

# Mohd Arif Anuar Mohd Salleh

## List of Publications by Year in descending order

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122  
papers

1,206  
citations

430874

18  
h-index

477307

29  
g-index

124  
all docs

124  
docs citations

124  
times ranked

550  
citing authors

#	ARTICLE	IF	CITATIONS
1	Mechanical properties of Sn-0.7Cu/Si <sub>3</sub> N <sub>4</sub> lead-free composite solder. <i>Materials Science &amp; Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2012, 556, 633-637.	5.6	76
2	Suppression of Cu <sub>6</sub> Sn <sub>5</sub> in TiO <sub>2</sub> reinforced solder joints after multiple reflow cycles. <i>Materials and Design</i> , 2016, 108, 418-428.	7.0	57
3	Rapid Cu <sub>6</sub> Sn <sub>5</sub> growth at liquid Sn/solid Cu interfaces. <i>Scripta Materialia</i> , 2015, 100, 17-20.	5.2	56
4	Effect of TiO <sub>2</sub> additions on Sn-0.7Cu-0.05Ni lead-free composite solder. <i>Microelectronics Reliability</i> , 2016, 65, 255-264.	1.7	54
5	Effects of Ni and TiO <sub>2</sub> additions in as-reflowed and annealed Sn-0.7Cu solders on Cu substrates. <i>Journal of Materials Processing Technology</i> , 2017, 242, 235-245.	6.3	54
6	Effect of Ni on the Formation and Growth of Primary Cu <sub>6</sub> Sn <sub>5</sub> Intermetallics in Sn-0.7wt.%Cu Solder Pastes on Cu Substrates During the Soldering Process. <i>Journal of Electronic Materials</i> , 2016, 45, 154-163.	2.2	51
7	Solderability of Sn-0.7Cu/Si <sub>3</sub> N <sub>4</sub> lead-free composite solder on Cu-substrate. <i>Physics Procedia</i> , 2011, 22, 299-304.	1.2	48
8	Development of a microwave sintered TiO <sub>2</sub> reinforced Sn-0.7wt%Cu-0.05wt%Ni alloy. <i>Materials and Design</i> , 2015, 82, 136-147.	7.0	43
9	In situ imaging of microstructure formation in electronic interconnections. <i>Scientific Reports</i> , 2017, 7, 40010.	3.3	43
10	Strength Development and Elemental Distribution of Dolomite/Fly Ash Geopolymer Composite under Elevated Temperature. <i>Materials</i> , 2020, 13, 1015.	2.9	42
11	The influence of ageing on the stabilisation of interfacial (Cu,Ni) <sub>6</sub> (Sn,Zn) <sub>5</sub> and (Cu,Au,Ni) <sub>6</sub> Sn <sub>5</sub> intermetallics in Pb-free Ball Grid Array (BGA) solder joints. <i>Journal of Alloys and Compounds</i> , 2016, 685, 471-482.	5.5	37
12	Characterising the polymorphic phase transformation at a localised point on a Cu <sub>6</sub> Sn <sub>5</sub> grain. <i>Materials Characterization</i> , 2018, 138, 113-119.	4.4	37
13	The effect of Bi on the microstructure, electrical, wettability and mechanical properties of Sn-0.7Cu-0.05Ni alloys for high strength soldering. <i>Materials and Design</i> , 2020, 186, 108281.	7.0	35
14	Bonding Strength Characteristics of FA-Based Geopolymer Paste as a Repair Material When Applied on OPC Substrate. <i>Applied Sciences (Switzerland)</i> , 2020, 10, 3321.	2.5	29
15	Non-Metal Reinforced Lead-Free Composite Solder Fabrication Methods and its Reinforcing Effects to the Suppression of Intermetallic Formation: Short Review. <i>Applied Mechanics and Materials</i> , 0, 421, 260-266.	0.2	27
16	Influence of Ni on the refinement and twinning of primary Cu <sub>6</sub> Sn <sub>5</sub> in Sn-0.7Cu-0.05Ni. <i>Intermetallics</i> , 2018, 102, 34-45.	3.9	27
17	Zn-Sn Based High Temperature Solder - A Short Review. <i>Advanced Materials Research</i> , 0, 795, 518-521.	0.3	25
18	Wettability, Electrical and Mechanical Properties of Sn-0.7Cu/Si <sub>3</sub> N <sub>4</sub> /Ni <sub>4</sub> Novel Lead-Free Nanocomposite Solder. <i>Advanced Materials Research</i> , 0, 277, 106-111.	0.3	23

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19	In Situ TEM Observations of Cu <sub>6</sub> Sn <sub>5</sub> Polymorphic Transformations in Reaction Layers Between Sn-0.7Cu Solders and Cu Substrates. <i>Jom</i> , 2016, 68, 2871-2878.	1.9	23
20	The Effect of Ni and Bi Additions on the Solderability of Sn-0.7Cu Solder Coatings. <i>Journal of Electronic Materials</i> , 2020, 49, 1-12.	2.2	23
21	Microstructure and porosity evolution of alkali activated slag at various heating temperatures. <i>Journal of Materials Research and Technology</i> , 2020, 9, 15894-15907.	5.8	22
22	Intermetallic Compound Formation on Solder Alloy/Cu-Substrate Interface Using Lead-Free Sn-0.7Cu/Recycled-Aluminum Composite Solder. <i>Advanced Materials Research</i> , 0, 620, 105-111.	0.3	18
23	The Influence of Sintering Temperature on the Pore Structure of an Alkali-Activated Kaolin-Based Geopolymer Ceramic. <i>Materials</i> , 2022, 15, 2667.	2.9	16
24	Imaging the Polymorphic Transformation in a Single Cu <sub>6</sub> Sn <sub>5</sub> Grain in a Solder Joint. <i>Materials</i> , 2018, 11, 2229.	2.9	15
25	Phase study of titanium dioxide nanoparticle prepared via sol-gel process. <i>IOP Conference Series: Materials Science and Engineering</i> , 2018, 343, 012011.	0.6	14
26	Relationship between free solder thickness to the solderability of Sn-0.7Cu-0.05Ni solder coating during soldering. <i>Journal of Materials Science: Materials in Electronics</i> , 2019, 30, 3669-3677.	2.2	14
27	Recent Developments in Steelmaking Industry and Potential Alkali Activated Based Steel Waste: A Comprehensive Review. <i>Materials</i> , 2022, 15, 1948.	2.9	14
28	Influence of Bi Addition on Wettability and Mechanical Properties of Sn-0.7Cu Solder Alloy. <i>Solid State Phenomena</i> , 2018, 273, 27-33.	0.3	12
29	Effect of kaolin geopolymer ceramic addition on the properties of Sn-3.0Ag-0.5Cu solder joint. <i>Materials Today Communications</i> , 2020, 25, 101469.	1.9	12
30	Isothermal Aging Affect to the Growth of Sn-Cu-Ni-1 wt.% TiO <sub>2</sub> Composite Solder Paste. <i>Key Engineering Materials</i> , 0, 700, 123-131.	0.4	9
31	Origin of Primary Cu <sub>6</sub> Sn <sub>5</sub> in Hypoeutectic Solder Alloys and a Method of Suppression to Improve Mechanical Properties. <i>Journal of Electronic Materials</i> , 2021, 50, 710-722.	2.2	9
32	Formation and Growth of Intermetallic Compounds in Lead-Free Solder Joints: A Review. <i>Materials</i> , 2022, 15, 1451.	2.9	9
33	Influence of Non-Metallic Particles Addition on Wettability, Intermetallic Compound Formation and Microhardness of Sn-0.7Cu Lead Free Solder Paste. <i>Solid State Phenomena</i> , 0, 280, 169-174.	0.3	8
34	Performance of Sn-3.0Ag-0.5Cu Composite Solder with Kaolin Geopolymer Ceramic Reinforcement on Microstructure and Mechanical Properties under Isothermal Ageing. <i>Materials</i> , 2021, 14, 776.	2.9	8
35	Microstructure, thermal behavior and joint strength of Sn-0.7Cu-1.5Bi/electroless nickel immersion gold (ENIG). <i>Journal of Materials Research and Technology</i> , 2021, 12, 1700-1714.	5.8	8
36	Thermal Properties of Different Recycled Acrylonitrile-Butadiene Rubber Glove (NBRr) Size and its Blend Ratios on SBR/NBRr Blends. <i>Advanced Materials Research</i> , 2013, 795, 377-382.	0.3	7

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37	Microstructural Observation and Phase Analysis of Sn-Cu-Ni (SN100C) Lead Free Solder with Addition of Micron-Size Silicon Nitride ( $\text{Si}_3\text{N}_4$ ) Reinforcement. Applied Mechanics and Materials, 2015, 754-755, 518-523.	0.2	7
38	Effects of Bi in Sn-Cu based lead-free solder alloys and interconnects. , 2017, , .		7
39	Self-cleaning property of graphene oxide/TiO <sub>2</sub> thin film. AIP Conference Proceedings, 2019, , .	0.4	7
40	Microstructure and growth kinetic study in Sn-Cu transient liquid phase sintering solder paste. Journal of Materials Science: Materials in Electronics, 2020, 31, 11077-11094.	2.2	7
41	Effects of Surface Finish on Sn-3.0Ag-0.5Cu Solder Joint Microstructure and Strength. Journal of Electronic Materials, 2021, 50, 855-868.	2.2	7
42	Influence of Sintering Temperature of Kaolin, Slag, and Fly Ash Geopolymers on the Microstructure, Phase Analysis, and Electrical Conductivity. Materials, 2021, 14, 2213.	2.9	7
43	Effect of Electromigration and Thermal Ageing on the Tin Whiskers' Formation in Thin Sn-0.7Cu-0.05Ga Lead (Pb)-Free Solder Joints. Coatings, 2021, 11, 935.	2.6	7
44	The effect of Ni on the growth morphology of primary $\beta_2$ -phase in an In-35wt%Sn alloy. Journal of Alloys and Compounds, 2022, 897, 163172.	5.5	7
45	Research Advances of Composite Solder Material Fabricated via Powder Metallurgy Route. Advanced Materials Research, 2012, 626, 791-796.	0.3	6
46	Wettability and Shear Strength of Sn-Cu-Ni- $\text{Si}_3\text{N}_4$ Composite Solder. Key Engineering Materials, 2016, 700, 152-160.	0.4	6
47	Corrosion Protection Of Mild Steel In Sea Water Using Chemical Inhibitor. IOP Conference Series: Materials Science and Engineering, 2018, 343, 012012.	0.6	6
48	The Effect of Geopolymer Ceramic Additions to The Wettability and Shear strength of Sn-Ag-Cu (SAC) Solder: A Preliminary Study. IOP Conference Series: Materials Science and Engineering, 2019, 551, 012081.	0.6	6
49	Properties of Sn-3wt%Ag-5wt%Cu alloys with Cu <sub>6</sub> Sn <sub>5</sub> intermetallics grain refined by Mg. Materials Today Communications, 2022, 31, 103221.	1.9	6
50	Compressive Strength and Morphology of Fly Ash Based Geopolymer as Artificial Aggregate with Different Curing Temperature. Key Engineering Materials, 2013, 594-595, 151-155.	0.4	5
51	Effect of TiO <sub>2</sub> on the Formation of Primary and Interfacial Cu <sub>6</sub> Sn <sub>5</sub> in Sn-0.7wt%Cu and Sn-0.7wt%Cu-0.05wt%Ni Solder Paste during Soldering. Key Engineering Materials, 0, 700, 161-169.	0.4	5
52	Growth Kinetic of Sn-0.7Cu-0.05Ni Solder Paste Subjected to Isothermal Aging. Solid State Phenomena, 0, 280, 163-168.	0.3	5
53	Influence of kaolin geopolymer ceramic additions to the wettability and electrical properties of Sn-3.0Ag-0.5Cu (SAC305) lead free solder. IOP Conference Series: Materials Science and Engineering, 2019, 701, 012033.	0.6	5
54	Effect of Ni on the Suppression of Sn Whisker Formation in Sn-0.7Cu Solder Joint. Materials, 2021, 14, 738.	2.9	5

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55	The Effect of Dipping Time to the Intermetallic Compound and Free Solder Thickness of Sn-Cu-Ni (SN100C) Lead-Free Solder Coating. Applied Mechanics and Materials, 2015, 754-755, 493-497.	0.2	4
56	Effect of Zinc Additions on Sn-0.7Cu-0.05Ni Lead-Free Solder Alloy. IOP Conference Series: Materials Science and Engineering, 2017, 238, 012012.	0.6	4
57	Characterization of Sn-3.5Ag-1.0Cu Lead-Free Solder Prepared via Powder Metallurgy Method. Advanced Materials Research, 2012, 501, 160-164.	0.3	3
58	The Effect of Different Sizes "Batu Reput" (Dolomite) as a Filler in SMR L and ENR-50. Advanced Materials Research, 2013, 795, 383-387.	0.3	3
59	Natural Rubber/Styrene Butadiene Rubber/Recycled Nitrile Glove (NR/SBR/rNBRg) Ternary Blend: Curing Characteristics and Swelling Test. Key Engineering Materials, 2013, 594-595, 634-638.	0.4	3
60	Effects of Recycled-Aluminum Additions on the Mechanical Properties of Sn-0.7Cu/Cu-Substrate Lead-Free Solder Joints. Advanced Materials Research, 0, 795, 446-450.	0.3	3
61	<i>In Situ</i> Soldering Process Technique by Synchrotron X-Ray Imaging. Applied Mechanics and Materials, 2015, 754-755, 508-512.	0.2	3
62	An Investigation of TiO <sub>2</sub> Addition on Microstructure Evolution of Sn-Cu-Ni Solder Paste Composite. MATEC Web of Conferences, 2016, 78, 01070.	0.2	3
63	The Effects of Gallium Additions on the Microstructure of Lead-Free Solder Materials: A Short Review. Solid State Phenomena, 2018, 280, 187-193.	0.3	3
64	Microstructure Evolution of Sn-Cu Based Solder Paste with Different Cu Concentration Subjected to Multiple Reflows. Solid State Phenomena, 2018, 280, 206-211.	0.3	3
65	Spontaneous Tin (Sn) Whisker Growth from Electroplated Tin and Lead-Free Tin Alloys Coatings: A Short Review. Solid State Phenomena, 2018, 280, 151-156.	0.3	3
66	Effect of rare-element (Ga) addition on the microstructure and mechanical properties of Sn-0.7Cu and Sn-0.7Cu-0.05Ni lead-free solder alloys. IOP Conference Series: Materials Science and Engineering, 0, 701, 012031.	0.6	3
67	Microstructure and Mechanical Properties of Geopolymer Ceramic Reinforced Sn-0.7Cu Solder. IOP Conference Series: Materials Science and Engineering, 2020, 864, 012041.	0.6	3
68	Influence of 1.5 wt.% Bi on the Microstructure, Hardness, and Shear Strength of Sn-0.7Cu Solder Joints after Isothermal Annealing. Materials, 2021, 14, 5134.	2.9	3
69	Effect of Kaolin Geopolymer Ceramics Addition on the Microstructure and Shear Strength of Sn-3.0Ag-0.5Cu Solder Joints during Multiple Reflow. Materials, 2022, 15, 2758.	2.9	3
70	Preparation of Cyclopentyl Trisilanol Silsesquioxanes - Modified Natural Rubber (CpSSQ(OH) <sub>3</sub> ENR-50) Composite Hybrid in the Presence of HCL Acid. Advanced Materials Research, 2013, 795, 251-255.	0.3	2
71	The Effect of Different Alkaline Treatment Condition on Flexural Properties of Kenaf Bast-Unsaturated Polyester Composite. Advanced Materials Research, 0, 795, 631-634.	0.3	2
72	Low and High Temperature Isothermal Aging Effect on Morphology and Diffusion Kinetics of Intermetallic Compound (IMC) for Sn-Cu-Si <sub>3</sub> N <sub>4</sub> Composite Solder. Key Engineering Materials, 0, 594-595, 666-670.	0.4	2

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73	Nickel (Ni) Microalloying Additions in Sn-Cu Lead-free Solder. Short Review. IOP Conference Series: Materials Science and Engineering, 2017, 209, 012084.	0.6	2
74	Microstructure and mechanical properties of lead-free Sn-Cu-Ni composite solder paste reinforced with silicon (Si) particles. AIP Conference Proceedings, 2017, , .	0.4	2
75	The Effect of Temperature on Tin Whisker Growth under Mechanical Stress. Solid State Phenomena, 2018, 280, 194-199.	0.3	2
76	Synchrotron Radiography of Sn-0.7Cu-0.05Ni Solder Solidification. Solid State Phenomena, 2018, 273, 66-71.	0.3	2
77	Fabrication of Novel Geopolymer Reinforced Tin Copper Solder in Suppressing Intermetallic Layer Growth. IOP Conference Series: Materials Science and Engineering, 2019, 551, 012091.	0.6	2
78	Development of Geopolymer Ceramic as a Potential Reinforcing Material in Solder Alloy: Short review. IOP Conference Series: Materials Science and Engineering, 2020, 743, 012023.	0.6	2
79	Microstructure, mechanical properties and corrosion analysis of Snâ€“0.7Cuâ€“+â€“Ga solders joints developed using green concentrated solar energy soldering method. Journal of Materials Science: Materials in Electronics, 2021, 32, 21709-21726.	2.2	2
80	Liquid/Solid Interaction of Sn-58Bi/Sn-3.0Ag-0.5Cu Dissimilar Joints during Soldering at Low Temperature by In-Situ Synchrotron Imaging. Jom, 2022, 74, 2760-2769.	1.9	2
81	Effects of immersion silver (ImAg) and immersion tin (ImSn) surface finish on the microstructure and joint strength of Sn-3.0Ag-0.5Cu solder. Journal of Materials Science: Materials in Electronics, 0, , .	2.2	2
82	Microstructure Evolution of Sn-3.5Ag-1.0Cu-0.5Ni/Cu System Lead Free Solder under Long Term Thermal Aging. Advanced Materials Research, 0, 620, 263-267.	0.3	1
83	Effect of Aging Time towards Intermetallic Compound (IMC) Growth Kinetics Formation for Sn-0.7Cu-Si&lt;sub>3&lt;/sub>N&lt;sub>4&lt;/sub> Composite Solder on Copper Substrate. Advanced Materials Research, 0, 795, 505-508.	0.3	1
84	Synthesis and Characterization of Electroless Copper Coated SiC Particles. Advanced Materials Research, 0, 795, 233-236.	0.3	1
85	Failure Investigation on Rusty Mesh Strainer of Petrochemical Plant. Advanced Materials Research, 2013, 795, 488-491.	0.3	1
86	Effect of Aging Temperature on the Intermetallic Compound (IMC) Formation of Sn-0.7Cu/Si&lt;sub>3&lt;/sub>N&lt;sub>4&lt;/sub> Composite Solder. Advanced Materials Research, 0, 795, 522-525.	0.3	1
87	Fabrication of Cu-SiC&lt;sub>p&lt;/sub> Composites via the Electroless Copper Coating Process for the Electronic Packaging Applications. Advanced Materials Research, 0, 795, 272-275.	0.3	1
88	Alteration of Solution Treatment Condition to the Precipitation Behavior A319 Alloy. Advanced Materials Research, 2013, 795, 679-683.	0.3	1
89	Influence of Activated Carbon Particles on Intermetallic Compound Growth Mechanism in Sn-Cu-Ni Composite Solder. MATEC Web of Conferences, 2016, 78, 01064.	0.2	1
90	Thermal and mechanical properties of Sn-Cu-Ni-XSiC composite solder. AIP Conference Proceedings, 2017, , .	0.4	1

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91	Microstructural and phase analysis of Sn-Cu-Ni-XSiC composite solder. AIP Conference Proceedings, 2017, , .	0.4	1
92	Grain Refinements of Cu<sub>6</sub>Sn<sub>5</sub> in Sn-3wt%Ag-5wt%Cu High Temperature Solder Alloys. Solid State Phenomena, 0, 273, 20-26.	0.3	1
93	Solidification Behavior of Sn Cu Based Peritectic Alloys: A Short Review. Solid State Phenomena, 2018, 273, 34-39.	0.3	1
94	Sn Whiskers Nucleation and Growth - Short Review. Solid State Phenomena, 2018, 280, 175-180.	0.3	1
95	The Effect of Copper Addition on the Properties of Sn-0.7Cu Solder Paste. IOP Conference Series: Materials Science and Engineering, 2018, 318, 012062.	0.6	1
96	Effect of Zn Additions on Thermal and Mechanical Properties of Sn-0.7Cu-xZn Solder Alloy. Solid State Phenomena, 0, 280, 200-205.	0.3	1
97	A study of geo-polymer as alternative material in automotive brake pad. AIP Conference Proceedings, 2021, , .	0.4	1
98	Microstructure evolution of Sn-Cu based solder paste on electroless nickel immersion gold (ENIG) surface finish subjected to multiple reflow cycles. AIP Conference Proceedings, 2021, , .	0.4	1
99	The Root Caused Analysis of Leaked Heat Exchanger Tube. Praktische Metallographie/Practical Metallography, 2015, 52, 157-176.	0.3	1
100	Controlling the distribution of porosity during transient liquid phase bonding of Sn-based solder joint. Materials Today Communications, 2022, 31, 103248.	1.9	1
101	FT-IR and Morphology of Different Recycled Acrylonitrile-Butadiene Rubber Glove (NBRgr) Size and its Blend Ratios of SBR/NBRr Blends. Advanced Materials Research, 0, 626, 1033-1037.	0.3	0
102	Research Development of Solder Materials and its Intermetallic Compound (IMC) Study. Advanced Materials Research, 2012, 626, 797-801.	0.3	0
103	The Effects of Tensile and Morphological Properties of Styrene Butadiene Rubber/Recycled Chloroprene Rubber (SBR/CRr) Blends. Advanced Materials Research, 0, 626, 802-806.	0.3	0
104	Intermetallic evolution between Sn-3.5Ag-1.0Cu-xZn lead free solder and copper substrate under long time thermal aging (x: 0, 0.1, 0.4, 0.7). , 2012, , .		0
105	Solder microstructure and intermetallic interface evaluation between Sn-3.5Ag-1.0Cu-xNi lead free solder under long time thermal aging (x: 0, 0.05, 0.2, 0.5). , 2012, , .		0
106	Thermal Properties of Sn-0.7Cu/re-Al Composite Lead-Free Solder. Advanced Materials Research, 2013, 795, 451-454.	0.3	0
107	Mixing Optimization of Sn-Cu-Si<sub>3</sub>N<sub>4</sub> via Powder Metallurgy Route for Composite Solder Fabrication. Key Engineering Materials, 0, 594-595, 765-769.	0.4	0
108	High Temperature Creep and Hydrogen Embrittlement Failure of a Steam Trap Bypass Tube. Advanced Materials Research, 2013, 795, 455-458.	0.3	0



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109	Metallurgical Failure Analysis of a Closed Recirculation System Water Cooling Pipe. Advanced Materials Research, 0, 795, 474-478.	0.3	0
110	Overview of Pathogenic Micro-Organisms Destruction in Contaminated Water by Oxide Photocatalysis. Advanced Materials Research, 2013, 795, 483-487.	0.3	0
111	Real time X-ray imaging of soldering processes at the SPring-8 synchrotron. , 2017, , .		0
112	Effect of silicon (Si) particles addition on melting temperature, intermetallic compound formation and solderability of Sn-Cu-Ni composite solder paste. AIP Conference Proceedings, 2017, , .	0.4	0
113	The Effect of Aggressive Corrosion Mediums on the Microstructure and Properties of Mild Steel. IOP Conference Series: Materials Science and Engineering, 2018, 374, 012044.	0.6	0
114	Enhancement of Microstructural and Physical Properties of Sn-0.7Cu Lead-Free Solder with the Addition of SiC Particles. Solid State Phenomena, 2018, 280, 181-186.	0.3	0
115	Protection of Tempered Aluminum Alloy in Contact with the Environment. IOP Conference Series: Materials Science and Engineering, 2018, 374, 012043.	0.6	0
116	Microstructure, Interfacial IMC and Wettability of Sn-0.7Cu-xZn Solder Alloy. Solid State Phenomena, 2018, 280, 157-162.	0.3	0
117	Thermal behaviour and microstructural analysis of Sn-0.7Cu alloy and Sn-0.7Cu soldered on electroless nickel/immersion gold. IOP Conference Series: Materials Science and Engineering, 2019, 701, 012023.	0.6	0
118	Solderability of Sn-0.7Cu-0.05Ni-xZn Solder Ball on Sn-0.7Cu and Sn-0.7Cu-0.05Ni Solder Coating. IOP Conference Series: Materials Science and Engineering, 2019, 551, 012094.	0.6	0
119	Impact of Thermal Ageing and Multiple Reflow on Lead Free Composite Solder : A Short Review. IOP Conference Series: Materials Science and Engineering, 2020, 957, 012063.	0.6	0
120	Solidification Behaviour of Sn-40Pb Lead Solder and Sn-0.7Cu Lead-free Solder. IOP Conference Series: Materials Science and Engineering, 2020, 864, 012036.	0.6	0
121	The Effect of Thermal Annealing on the Microstructure and Mechanical Properties of Sn-0.7Cu-xZn Solder Joint. Metals, 2021, 11, 380.	2.3	0
122	Synthesis of Kaolin Geopolymer as Ceramic Reinforcement in Lead-Free Solder. Journal of Physics: Conference Series, 2022, 2169, 012019.	0.4	0